Amendments to the Specification:

Please amend paragraph [0017] on page 7 as follows:

[0017] The wiring layer is formed on one of the main surfaces of the carrier base (that is, one of the two large surfaces of the sheet). In this specification including the following description, a main surface of the carrier base is merely referred to as a "surface", and the main surface of the carrier base on which the wiring layer is formed is referred to as a "transfer surface of a carrier base on which a wiring layer is formed." With respect to other sheet-like members, the main surfaces are merely referred to as a "surface."

Please amend paragraph [0033] on page 16 as follows:

[0033] The wiring transfer sheet of the present invention is also identified as a wiring transfer sheet including a carrier base and a wiring layer formed ~~thereon~~ on a transfer surface of the carrier base, wherein the wiring layer is to be transferred to a receiving surface of an object. The exposed area of ~~a~~ the transfer surface of the carrier base is for making an average of ten point heights of irregularities (i.e., a ten-point mean roughness) Rz in the range of 2 to 12 μm within an area of the object, which area contacts the exposed area. Such a wiring transfer sheet makes the surface of the wiring board entirely flat, while making it a surface having concavities and convexities microscopically. The wiring board having such a surface has an excellent initial mounting characteristic, and adheres well to a material stacked thereon.

Please amend paragraph [0034] spanning pages 16 and 17 as follows:

[0034] The carrier base of the wiring transfer sheet is preferably made from a material which is not compatible (i.e., not mixable or soluble) with a material of an object which the carrier base is to contact and to which the wiring layer is to be transferred, that is, an electrically insulating substrate for a wiring board. The carrier base of such a material is easily removed from the electrically insulating substrate after the wiring layer is has been transferred. The material for the carrier base is selected depending on the kind of the object (that is, the material of the electrically insulating substrate). When the electrically insulating substrate is, for example, one containing an epoxy resin, the carrier base is preferably made of a fluorine-containing resin. Since the

fluorine-containing resin exhibits an excellent release-ability as to the electrically insulating substrate and has an excellent heat resistance, it does not decompose by heating and pressurization and is not compatible with the electrically insulating substrate. Therefore, the wiring transfer sheet having the carrier base made from of the fluorine-containing resin makes it possible to roughen a surface of the electrically insulating substrate with ease. Particularly, when the carrier base has fine concavities on the exposed area of the surface, such a wiring transfer sheet makes it possible to form fine convexities on a surface of the electrically insulating substrate with ease.

Please amend paragraph [0076] spanning pages 38 and 39 as follows:

[0076] The wiring transfer sheet of the present invention is a sheet which includes a carrier based and a wiring layer formed on a transfer surface of the carrier base. The carrier base is preferably made from a material which is not compatible (i.e., not mixable or soluble) with the material of an object to which the wiring layer is to be transferred, by heating and pressurizing a layered body which consists of the wiring transfer sheet and the object upon transferring the wiring layer. The material for the carrier base is selected from an organic resin and a metal, depending on the material of the electrically insulating substrate. When the electrically insulating substrate contains an epoxy resin, a polyimide resin, a cyanate resin, a polyphenylene ether (PPE) resin, or a polytetrafluoroethylene resin, the carrier base is preferably made from a material selected from polyimide, a fluorine-containing resin, and a heat resistant epoxy resin. Further, the carrier base is preferably made from a material which ~~is~~ can be peeled off from the wiring layer in a step of removing the carrier base. From this viewpoint, the carrier base is preferably made of a polyimide resin or a fluorine-containing resin.

Please amend paragraph [0095] spanning pages 46 and 47 as follows:

[0095] In Fig. 1, a wiring transfer sheet of Embodiment 1 of the present invention and a wiring board which is produced using the wiring transfer sheet are schematically shown in sectional views. Fig. 1(a) shows a wiring transfer sheet 100 wherein a wiring layer 102 is formed in a predetermined pattern on a surface of a carrier base 101. Fig. 1(b) shows an enlarged view of Area B which is an exposed area of a surface of the carrier base is on which the wiring layer is formed.

Fig. 1(c) shows an enlarged view of Area A in the vicinity of a the wiring layer of the wiring transfer sheet. Fig. 1(d) shows a wiring board ~~100~~ 110 which is obtained by transferring a wiring layer 103 to an electrically insulating substrate 104 by using the wiring transfer sheet shown in Fig. 1(a). Fig. 1(e) shows an enlarged view of an Area D that is an exposed surface of the electrically insulating substrate, which is a part of a surface of the wiring board which surface has the wiring layer. Fig. 1(f) shows an enlarged view in the vicinity of the wiring layer of the wiring board.

Please amend paragraph [0097] spanning pages 47 and 48 as follows:

[0097] The wiring board is obtained by superposing the wiring transfer sheet on the an electrically insulating substrate for a wiring board with the wiring layer in contact with a surface of the electrically insulating substrate followed by heating and pressurization so as to transfer the wiring layer to the electrically insulating substrate. The structure of the wiring layer thus obtained is as shown Fig. 1(d). In this wiring board 110, the wiring layer 103 is entirely buried in the electrically insulating substrate 104, and an exposed surface of the wiring layer 103 is flush with an exposed surface of the electrically insulating substrate 104. This is because the wiring layer 102 protrudes ~~in~~ from the wiring transfer sheet 100 shown in Fig. 1(a). During the step of transferring the wiring layer, pressure is applied so that the wiring layer is brought into contact with the object without a gap therebetween, whereby the protruding wiring layer is buried in the electrically insulating substrate.

Please amend paragraph [0103] on page 50 as follows:

[0103] A wiring board 310 as shown in Fig. 3(c) is obtained by transferring the wiring layer of this wiring transfer sheet to a surface of an electrically insulating substrate through heating and pressurization. As shown in Fig. 3(d), in the wiring board 310, the transferred wiring layer 303 protrudes from the surface of the electrically insulating substrate 304. When a semiconductor bare chip or the like is mounted on the surface of the wiring layer 303, the gap between the semiconductor bare chip and the surface of the wiring board is larger compared with the case where the bare chip is mounted on the wiring board shown in ~~Fig. (d)~~ Fig. 1(d). As described above, the larger the gap is, the easier a sealing resin for protecting the mounting portion is injected. As described above with reference to Fig. 1(f), the surface of the wiring layer 303 has convexities.